

ABSTRACT

A multilayer printed wiring board of the present invention includes (a) an inner layer material (1) that includes an insulating substrate (3), an 5 inner conductive pattern (2, 2a, 2b) formed of a metal foil and disposed on both sides of the insulating substrate, respectively, and an interstitial via hole (4, 4a, 4b), (b) an insulating resin (5b) disposed on both sides of the inner layer material, respectively, (c) an outer conductive pattern (8) disposed on the surface of the insulating resin and (d) a surface via hole (7) electrically connecting between the inner conductive pattern and the outer conductive pattern. The outer conductive pattern is formed of a metal foil (5) with insulating resin comprising the insulating resin (5b) and a metal foil (5a) adhered to the insulating resin (5b). An interstitial via hole has a conductive paste that is applied to a through hole. A surface via hole has a metal plating (5c) that is applied to a non-through hole. With this structure, the excellent ability to accommodate wiring is realized. The strength in adhesion between the insulating resin and the conductive pattern for outer layer is enhanced remarkably with a resulting contribution to maintaining an excellent components mounting strength even when a outer conductive pattern becomes small in dimension.